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U.S. PATENT	DOCUMENTS									
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102 4 6 7 0 7 7 0 06/02/87 Tai		-	<u> </u>							
4 7 8 3 6 9 5 11/08/88 Eichelber	ger et al.		-	1/						
4 8 8 4 1 2 2 11/28/89 Eichelber	ger et al.		ļ,	<i>X</i> _						
4 9 3 3 0 4 2 05/12/90 Eichelben	per et al.	 	/	 						
4949148 08/14/90 Bartelink		1	<u> </u>							
5 0 1 9 5 3 5 05/28/91 Wojarowsk	l et al.									
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OTHER DOCUMENTS (Including Author, Ti	tle, Date, P	ertiner	t Page,	Etc.)						
J. Pilchowski et al., "Silicon M	M with Full	y Intec	rated Co	oling,"						
HDI Magazine, May 1998, p.48.			•	···						
J. Holf et al., "System Integrat.	ion for High	Freque	ncy Appl:	ications	<u></u>					
Intl. J. of Microelectronics and	Intl. J. of Microelectronics and Electronic Packaging 21, 119 (1998).									
C.A. Armiento et al., "Gigabit Transmitter Array Modules on Silicon										
	Waferboard," IEEE Transactions on Components, Hybrids and Manufacturing									
M. Töpper et al., "Embedding Tech	mology—A Ch	ip-Fin	st Approa	ch Using	BCB,"					
1997 Intl. Symposium on Advanced		terial	s, p. 11.							
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A.	. ,										-				
	Jeffrey T. Butler et al., "Advanced Multichip Module Packaging of Micromechanical Systems," 1997 Intl. Conf. on Solid-State Sensors and														
	Actuators, p. 261.														
Robert Bondreau et al., "Wafer Scale Photonic-Die Attachment," IEEE Trans. on Components, Packaging and Manufacturing Technology-Part B,															
	21, 1070 (1998).														
	Z. Xiao et al., "Low Temperature Silicon Wafer-to-Wafer Bonding with														
			Nic	cke	el.	Si	i 1 i	icio	de." J. El	lectrochem. So	oc. 145. 1	360 (19	998).	•	
Nickel Silicide," J. Electrochem. Soc. 145, 1360 (1998). R. Fillion et al., "Plastic Encapsulated MCM Technology for High Volume,															
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	Page 3 of 3		FILING DATE		GROUP						
		U	J.S. PATENT DOCUMENTS								
*EXAMINER INTIAL	DOCUMENT NUMBER	DATE .	MAME	aiss	SUBCLASS	• •	FLING DATE IF APPROPRIATE				
De	6,025,638	02-15-00	POGGE ET AL.								
	6,066,513	05-23-00	POGGE ET AL.								
	5,998,868	12-07-99	POGGE ET AL.								
	6,087,199	07-11-00	POGGE ET AL.								
	5,258,236	11-02-93	Arjavalingam et al.								
10	6,355,501	03-12-02	Fung et al.								
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		FORE	IGN PATENT DOCUMENTS	· ·							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANS YES	NO NO				
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	OTHER DOCUM	ENTS (Including	Author, Title, Date, Pertinent	Pages, Etc.)							
	A Novel Chip-Stapp. S19-S22, Eric	"A Novel Chip-Stack Package" - Solid State Technology, April 2002, www.solid-state.com, pp. S19-S22, Eric Beyne, IMEC, Leuven, Belgium									
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